



HMPS8599

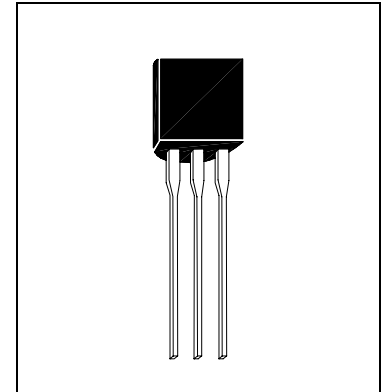
PNP SILICON TRANSISTOR

Description

HMPS8599 is designed for general purpose amplifier applications.

Features

- Low Collector-Emitter Saturation Voltage
- HMPS8599 is complementary to HMPS8099



Absolute Maximum Ratings

- Maximum Temperatures
 Storage Temperature -55 ~ +125 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
 VCBO Collector to Base Voltage -80 V
 VCES Collector to Emitter Voltage..... -80 V
 VEBO Emitter to Base Voltage -5 V
 IC Collector Current -500 mA

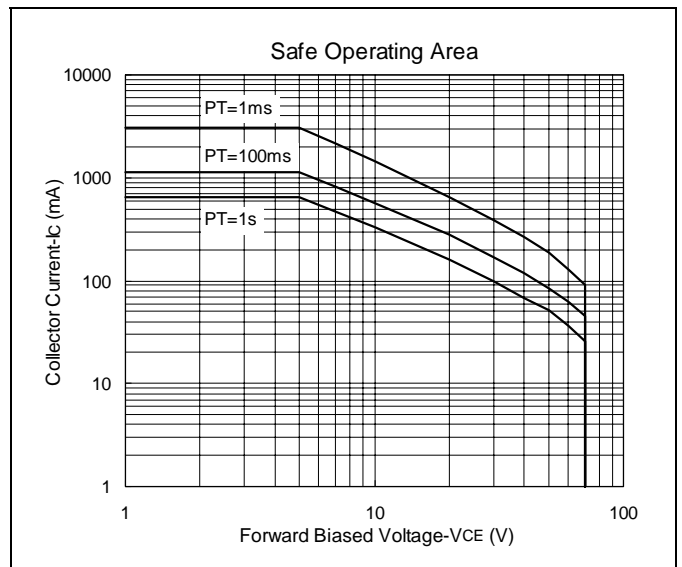
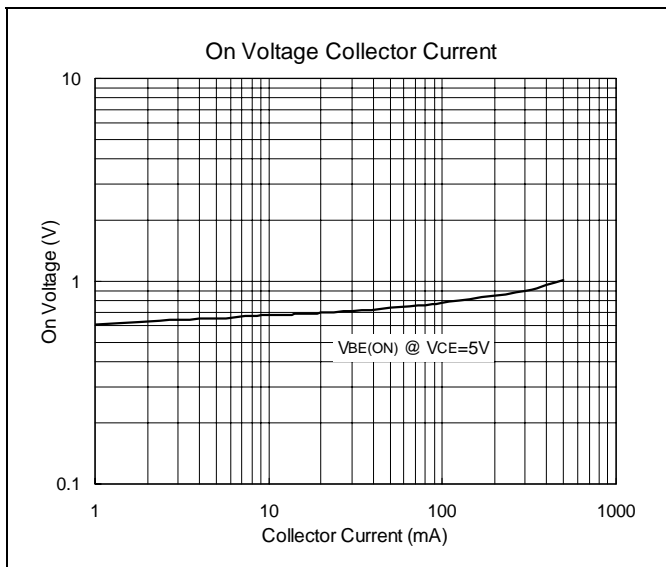
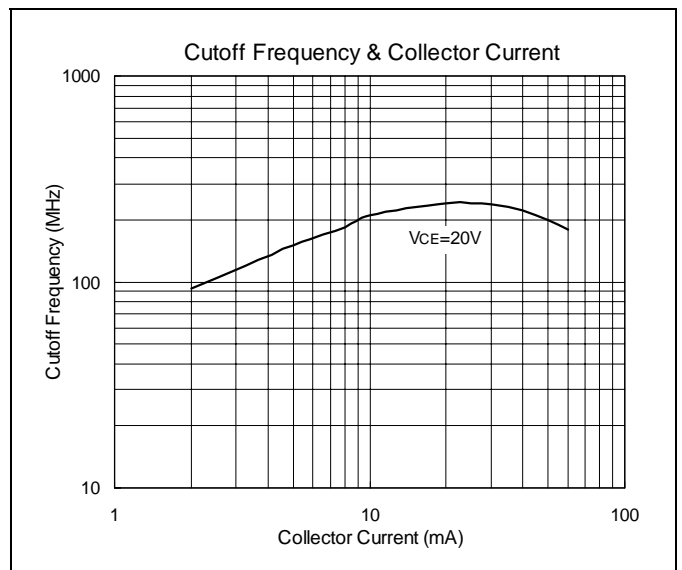
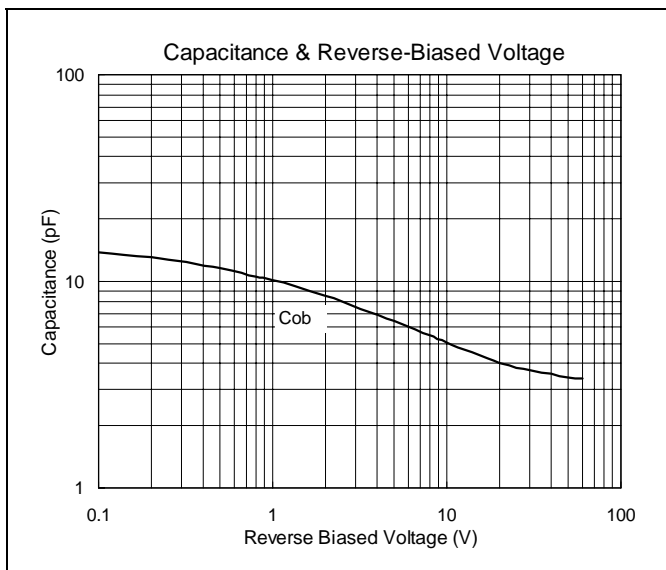
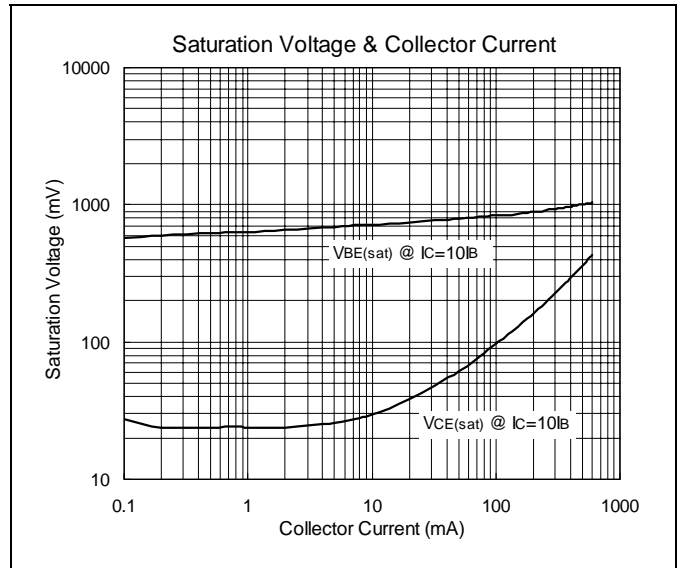
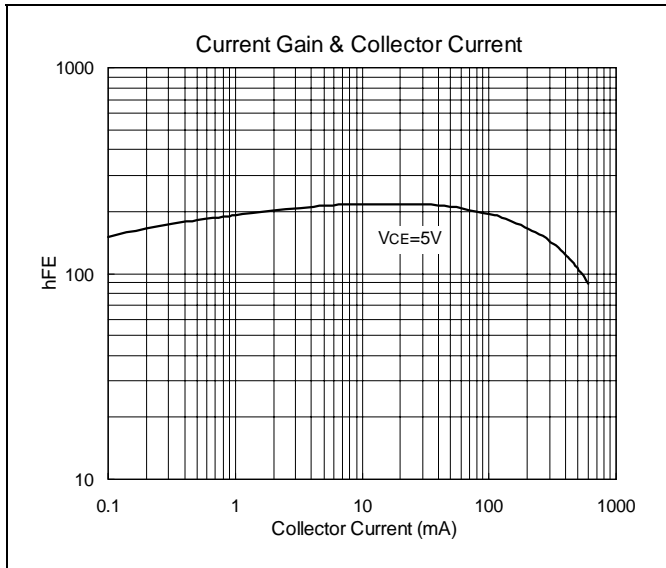
Characteristics (Ta=25°C)

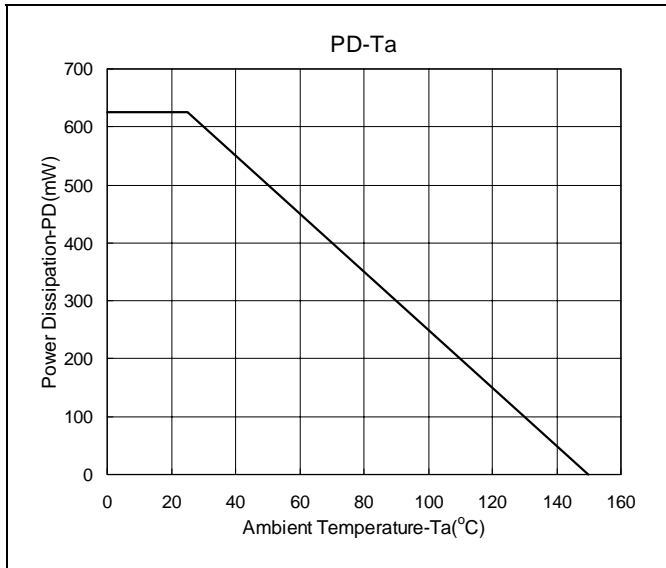
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	-80	-	-	V	IC=-100uA, IE=0
BVCEO	-80	-	-	V	IC=-10mA, IB=0
BVEBO	-5	-	-	V	IE=-10uA, IC=0
ICBO	-	-	-100	nA	VCB=-80V, IE=0
IEBO	-	-	-100	nA	VEB=-4V, IC=0
ICEO	-	-	-100	nA	VCE=-60V, IB=0
*hFE1	100	-	300		IC=-1mA, VCE=-5V
*hFE2	100	-	-		IC=-10mA, VCE=-5V
*hFE3	75	-	-		IC=-100mA, VCE=-5V
*VCE(sat)1	-	-	-0.4	V	IC=-100mA, IB=-5mA
*VCE(sat)2	-	-	-0.3	V	IC=-100mA, IB=-10mA
VBE(on)	-0.6	-	-0.8	V	IC=-10mA, VCE=-5V
fT	150	-	-	MHz	VCE=-5V, IC=-10mA, f=100MHz
Cob	-	-	8	PF	VCB=-5V, IE=0, f=1MHz

*Pulse Test : Pulse Width ≤380us, Duty Cycle≤2%



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
 HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1. Emitter 2. Base 3. Collector

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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